

Provided by: CHI MEI MATERIALS TECHNOLOGY CORP.

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| Subject        | Announcement for subsidiary, KUNSHAN CHIMEI Materials Technology Corp. of resolution of capital increase by an issuance of new common shares                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |
| Date of events | 2017/11/09                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                      |
| Statement      | <ol style="list-style-type: none"> <li>1.Date of the board of directors resolution: 2017/11/09</li> <li>2.Source of capital increase funds: Cash capital increase</li> <li>3.Number of shares issued: N/A</li> <li>4.Par value per share: N/A</li> <li>5.Total monetary amount of the issue: USD\$146,000,000</li> <li>6.Issue price: N/A</li> <li>7.Number of shares subscribed by or allotted to employees: N/A</li> <li>8.Number of shares publicly sold: N/A</li> <li>9.Ratio of shares subscribed by or allotted as stock dividends to existing shareholders: 100%</li> <li>10.Method of handling fractional shares and shares unsubscribed by the deadline: N/A</li> <li>11. Rights and obligations of the newly issued shares: Same as issued shares.</li> <li>12. Utilization of the funds from the capital increase: In response to funding of the second production line (2.5 meters) construction, the license fee of technology licensing agreement with Nitto Denko Corp., and RTP equipment.</li> <li>13. Any other matters that need to be specified: Chairman is fully authorized to manage all the related matters.</li> </ol> |